Product / Process Change Notification



N° 2019-185-A2

Dear	Customer
veai	Custoniei

please find attached our INFINEON Technologies PCN:

Final PCN: Several changes affecting Gen 5P Mosfets for D2PAK, DPAK, TO220 packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-04-12.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
 Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon Technologies to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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Products affected Please refer to attached affected product list 1_cip19185_A2

Detailed Change Information

Subject: Final PCN: Several changes affecting Gen 5P Mosfets for D2PAK, DPAK, TO220

packages

Reason / Motivation: Production consolidation

Description	<u>Old</u>	New	
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip backside)	Cr/Ni/Ag Sputter Process	Ti/Ni/Ag Evaporation Process	
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)	Al/Si	Al/Si/Cu	
PROCESS - WAFER PRODUCTION: Move of all or part of wafer fab to a different location/site/subcontractor	Infineon Technologies Americas Corp., Temecula, United States EPISIL Technologies Inc., Taiwan		
PROCESS - ASSEMBLY: Change in leadframe dimensions	Dpak part AUIRFR5410TRL only: Single gage leadframe Dpak part AUIRFR5410TRL only gage leadframe		
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)	•	TFME Only TO220 and Dpak: Bare Cu in all area	
PROCESS - ASSEMBLY: Die attach material	Dpak parts 94-4103PBF, 94- 4918PBFonly: Die Attach material 44- 0014	Dpak parts 94-4103PBF, 94-4918PBF only: Die attach material 44-0314	
	Dpak parts AUIRFR5305, AUIRFR5305TR, AUIRFR5305TRL only: 12 mil Al bond wire	Dpak parts , AUIRFR5305, only: AUIRFR5305TRL only: 10 mil Al bond wire	
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	TO220 only: MG15F-35A	TFME only TO220 only: KE-G300BH	
PROCESS - ASSEMBLY: Change of product marking	TO220 and Dpak: No Site code	TFME affected only: TO220 and Dpak; Site Code M	
	TO220 and Dpak: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	TO220 and Dpak: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd(TFME)	

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TEST FLOW: Americas Corp., Temecula, United

Move of all or part of electrical States

wafer test and/or final test to a TO220 and Dpak: Final Test

different location/site/subcontractor Rectificadores Internacionales, S.A. de

C.V., Tijuana , Mexico

Wafer Probe site: Infineon Technologies Wafer Probe site: EPISIL Technologies

Inc., Taiwan

TO220 and Dpak: Final Test,

Rectificadores Internacionales, S.A. de

C.V., Tijuana, Mexico and Tongfu Microelectronics Co., Ltd(TFME)

Product Identification

Traceability assured via Lot number an date code.

Anticipated Impact of Change

No expected impact on electrical performance. Quality and reliability verified by

qualification.

DeQuMa-ID(s): SEM-PW-06 / SEM-PW-07 / SEM-PW-13 / SEM-PA-03 / SEM-PA-

04 / SEM-PA-07 / SEM-PA-08 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-TF-01

Attachments

1_cip19185_A2 affected product list

3_cip19185_A2 customer information package

Time Schedule

Final qualification report	2021-02-28
First samples available	2021-02-28
Intended start of delivery [1]	2021-10-31
Last Order Date (LOD) [2]	2021-04-30
Last Delivery Date (LDD) [3]	2021-10-31

^[1] Provided date or earlier after customer approval

If you have any questions, please do not hesitate to contact your local Sales Office.

^[2] Last time buy volume to be placed latest until LOD

^[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

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Sales name	SP number	OPN	Package
94-4059PBF	SP001613642	94-4059PBF	PG-TO220-3-904
94-4103PBF	SP001614182	94-4103PBF	PG-TO252-3-901
94-4373PBF	SP001613632	94-4373PBF	PG-TO220-3-904
94-4918PBF	SP001522624	94-4918PBF	PG-TO252-3-901
AUIRF4905	SP001519228	AUIRF4905	PG-TO220-3-904
AUIRF4905S	SP001520184	AUIRF4905S	PG-TO263-3-901
AUIRF4905STRL	SP001517998	AUIRF4905STRL	PG-TO263-3-901
AUIRF5210STRL	SP001519458	AUIRF5210STRL	PG-TO263-3-901
AUIRF6215	SP001521586	AUIRF6215	PG-TO220-3-904
AUIRF6215S	SP001520176	AUIRF6215S	PG-TO263-3-901
AUIRF6215STRL	SP001522066	AUIRF6215STRL	PG-TO263-3-901
AUIRFR5305	SP001517358	AUIRFR5305	PG-TO252-3-901
AUIRFR5305TR	SP001517328	AUIRFR5305TR	PG-TO252-3-901
AUIRFR5305TRL	SP001519556	AUIRFR5305TRL	PG-TO252-3-901
AUIRFR5410TRL	SP001521222	AUIRFR5410TRL	PG-TO252-3-901
AUIRFR6215	SP001517590	AUIRFR6215	PG-TO252-3-901
AUIRFR6215TRL	SP001522196	AUIRFR6215TRL	PG-TO252-3-901
AUIRFR9024NTRL	SP001518586	AUIRFR9024NTRL	PG-TO252-3-901
AUXDIF4905	SP001597414	AUXDIF4905	PG-TO220-3-904
AUXDIF6215STRL	SP001518900	AUXDIF6215STRL	PG-TO263-3-901